

HSBC OVERSEAS SCHOLARSHIP 2020/21 UNIVERSITY RECOMMENDATION FORM

APPLICANT'S PERSONAL INFORMATION

Name: _____ Chinese name: _____

Gender: _____ Birth date: _____ HK I/D card no.: _____

Place of birth: _____ Years of residency in Hong Kong: _____

Citizenship(s): _____

Father's occupation: _____ Mother's occupation: _____

Family¹ income²: HKD _____ per month Number of family members: _____

Recipient of government loan (Y/N): _____ Amount: HKD _____

Recipient of government grant / subsidies / allowances (Please specify type): _____ Amount: HKD _____

Home address: _____

Contact number (s): _____ E-mail address: (school) _____ (permanent) _____

Overseas residency / studying / travelling experience (Y/N): _____ If yes, duration/details: _____

Hobbies: _____

Please affix
recent photo here

Name of current local university: _____

Name of current degree course: _____ Duration: _____ Current year of study: _____

GPA score: _____
CGPA 2019/20 1st semester 2018/19 (if applicable) *Please attach transcript for reference*

Name of target overseas university: _____

Choice of discipline at the overseas university: _____

SUMMARY OF RATING

(to be completed by current university):

	Excellent	Good	Satisfactory
Intellectual ability	_____	_____	_____
Analytical power	_____	_____	_____
Creativity	_____	_____	_____
Leadership	_____	_____	_____
Communication skills	_____	_____	_____
All-roundedness	_____	_____	_____
Commitment to Hong Kong	_____	_____	_____

1 "Family" means the applicant, applicant's spouse, parents, siblings, children and any other persons who are financially dependent on the aforementioned members.

2 Please note that the applicant may be required to submit supporting documentation to substantiate his/her declaration.

PERSONAL INFORMATION COLLECTION STATEMENT

Purpose of collection

The personal data provided in this form and any other information (the “Information”) that may be provided for the purposes of the application for “HSBC Overseas Scholarship 2020/21” (the “Programme”) and the enrolment for “HSBC Hong Kong Scholars Network” (the “Network”) will be used by the Hongkong Bank Foundation (the “Foundation”) and The Hongkong and Shanghai Banking Corporation Limited (“HSBC”) and their agents/contractors for one or more of the following purposes and any directly related purpose, in respect of the Programme and the Network:

- (i) to consider, process and administer your application, and serve any directly related purposes, e.g. processing and administering the scholarship under the Programme (if granted), and to communicate with you.
- (ii) to be contacted by the Network (if granted)
 - a. to check, verify and maintain the Members’ status;
 - b. to keep and update the Members’ contact records;
 - c. to communicate with and provide updates and information to you;
 - d. to inform you of or invite you to events, activities and programmes of or organised by the Network or other events, activities and programmes considered by the Network to be relevant to or of interest to Members;
 - e. to compile statistics and conduct research of the operation of the Network
- (iii) any other purposes as may be required, authorised or permitted by any law and/or regulation.

It is voluntary for you to provide your personal data to the Foundation and HSBC. If you fail to supply any of the Information required by this form, your application may not be processed.

Access to personal data

Except where there is an exemption provided under the Personal Data (Privacy) Ordinance (Cap. 486), you have the right to request access to and correction of your personal data provided in this form when the data have not been erased. Your right of access includes the right to obtain a copy of your personal data provided in this form subject to payment of a fee.

Request and enquiry

Your request for access to personal data or enquiry regarding personal data privacy policy should be addressed to:

The Data Protection Officer
The Hongkong and Shanghai Banking Corporation Limited
PO Box 72677
Kowloon Central Post Office
Hong Kong
Re: HSBC Overseas Scholarship 2020/21
E-mail: dfv.enquiry@hsbc.com.hk

DECLARATION BY THE APPLICANT

I, _____ (Name in full), understand that I am required to disclose anything that may be considered to be an actual or potential conflict of interest with regard to my application for a HSBC Scholarship. Examples of potential conflicts of interest include, but are not limited to, previous or current student apprenticeships with HSBC and having close relatives³ or individuals with whom the applicant has a personal relationship⁴ with working in HSBC.

I declare that:

I have no actual or potential conflict of interest that could directly or indirectly affect my application for a HSBC Scholarship. I will report such actual or potential conflict of interest should it arise.

I have held the following position in HSBC and/or have a close relative or someone with whom I have a personal relationship with in HSBC. I provide the relevant information below for your assessment of conflict of interest:

Student internship / placement in HSBC:

Department: _____

Internship / placement period: _____

Name of supervisor: _____

Close relatives or those with whom the applicant has a personal relationship with working in HSBC:

Name: _____

Job title: _____

Relationship with the Applicant: _____

Name: _____

Job title: _____

Relationship with the Applicant: _____

Any other actual or potential conflict of interest:

³ "Close relative" means spouse, parents, step parents, siblings, step siblings, children, step children, grandparents or the spouse of any of these and aunts, uncles, nephews or nieces.

⁴ "Personal relationship" means relationships with family members, friends and partnerships.

I declare that the Information provided in this Scholarship application is accurate, true and complete to the best of my knowledge. I am aware that the Foundation/HSBC will rely on such Information and consent to the Foundation/HSBC relying on the Information provided by me to determine my eligibility for the scholarship and the amount of the scholarship to be offered to me.

I confirm that I have carefully read and fully understand the “Personal Information Collection Statement” (the “PICS”) set out above. I accept the PICS and the purposes of use of the Information set out in it.

I confirm that each of the family members and other persons in respect of which the Information is provided in or in relation to this application (the “Relevant Person(s)”) has been notified of and agreed to the PICS and the purposes of use of the Information set out in it. I shall advise each Relevant Person that he/she has rights of access to, and correction of, his/her personal data. I agree to inform the Foundation/HSBC promptly in writing if I am not able or have failed to comply with the obligations set out in this paragraph in any respect.

I authorise and consent to my university releasing my personal data held by it to the Foundation/HSBC in order for it to use such information for such purposes set out in the PICS.

I authorise the Foundation to (i) transfer the Information to HSBC and for HSBC to use the Information for such purposes set out in the PICS; and (ii) release the results of my application to my university or institution.

Signature of the Applicant: _____

Name in full: _____

HKID Number: _____

Date: _____

The data collected will be kept confidential and used by the Hongkong Bank Foundation/HSBC to process the scholarship application.

**HSBC OVERSEAS SCHOLARSHIP 2020/21
STUDENT UNDERTAKING FORM**

To be completed by applicant and guarantor/s

To: _____
(name of university in Hong Kong)

In consideration of your awarding me the HSBC Overseas Scholarship, I, _____,
(name in English)

_____, the undersigned, hereby declare that the information I have submitted to the
(name in Chinese)

_____ and _____
(name of university in Hong Kong) *(name of university outside Hong Kong)*

is accurate and I have no overseas residency / extensive studying experience.

In addition, I understand that the Scholarship will go towards tuition fees, a minimum economy return airfare, reasonable room and board costs, books and a small portion of living expenses,

and I agree to:

- 1) Abide by the policies and requirements of both the local and overseas universities;
- 2) **Participate in and complete the Hong Kong Young Ambassador Scheme**, a three-week full-time summer programme from mid-July to early August, organised by the Tourism Commission of the Hong Kong Special Administration Region Government and The Hong Kong Federation of Youth Groups, and to act as a goodwill ambassador for Hong Kong while abroad, **or** participate in an alternate programme similar to the Hong Kong Young Ambassador Scheme, with prior written approval from HSBC; and
- 3) Participate actively in campus life and the community while overseas.

Signed by

(Applicant)

In the presence of

(Signature of Witness)
(must be different from Guarantor)

To be completed by Guarantor/s

In consideration of your accepting the above Undertaking from the applicant for the purposes stated thereon, I/we, the undersigned, hereby guarantee the due performance by the applicant of the Undertaking.

(Signature of Guarantor/s)

Name/s: _____

Name: _____

Relationship: _____

Address: _____

Address: _____

Date: _____

Date: _____